

## ABSTRACT

Provided are a laminate including an adhesive layer that can implement easy peeling when a semiconductor substrate and a support substrate are separated after processing of the semiconductor substrate and can suppress deformation of a bump, and the like.

A laminate includes a semiconductor substrate with a bump; a support substrate; a protective adhesive layer formed so as to be in contact with the semiconductor substrate with a bump; and a peeling adhesive layer formed between the protective adhesive layer and the support substrate,

in which the protective adhesive layer is formed of a protective adhesive composition, and the protective adhesive composition contains a component (A) which is cured by a hydrosilylation reaction and does not contain a peeling agent component (B) which does not cause a curing reaction, and

the peeling adhesive layer is formed of a peeling adhesive composition, and the peeling adhesive composition contains a component (A) which is cured by a hydrosilylation reaction and a peeling agent component (B) which does not cause a curing reaction.

FIG. 1